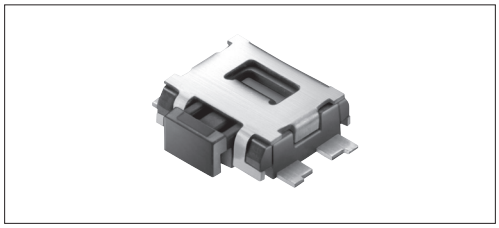
SKSC

1.25mm Height Low-profile Side Push（Surface Mount Type）

1.25mm Height Low-profile Side push Type (Surface Mount) SKSC Series.



Typical Specifications

Items	Specifications
Rating （max.）	50mA 12V DC
Rating （min.）	10μA 1V DC
Initial contact resistance	100mΩ max.
Travel （mm）	0.2

Product Line

Sidepush Type

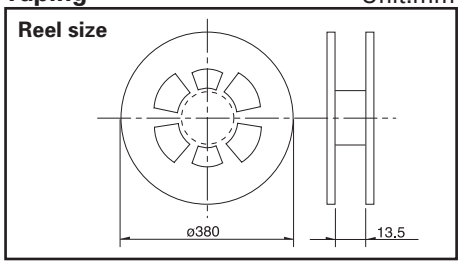
Product No.	Operating force	Operating direction	Operating life (5mA 5V DC)	Guide bosses	Minimum order unit (pcs.)	
					Japan	Export
SKSCLCE010	1.6N	Sidepush	100,000cycles	Without	5,000	
SKSCLAE010	2.2N					
SKSCLDE010	1.6N			With		
SKSCLBE010	2.2N					

With Ground Terminal Type

Product No.	Operatingforce	Operating direction	Operating life (5mA 5V DC)	Guide bosses	Minimum order unit (pcs.)	
					Japan	Export
SKSCPCE010	1.6N	Sidepush	100,000cycles	Without	5,000	
SKSCPAE010	2.2N					
SKSCPDE010	1.6N			With		
SKSCPBE010	2.2N					

Packing Specifications

Taping Unit:mm

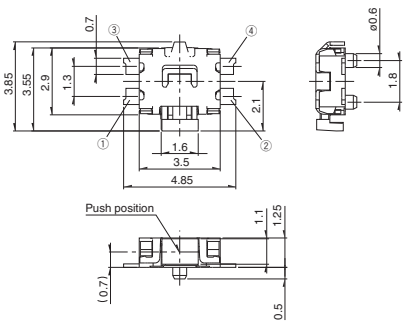
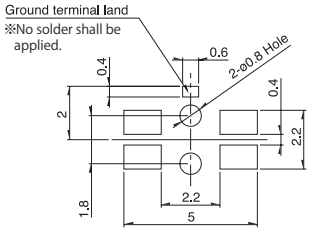


Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
1 reel	1 case / Japan	1 case / export packing		
5,000	50,000	50,000	12	401 × 401 × 214

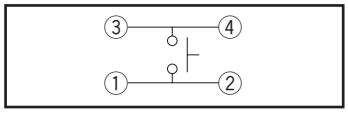
Note For reels of 330mm diameter, please inquire.

Dimensions

Unit:mm

Style	PC board mounting hole and land dimensions (Viewed from switch mounting face)
	

Circuit Diagram



Refer to **P.288** for soldering conditions.

■ List of Varieties

Type		Sharp Feeling Type										
		Surface Mount										
Series		SKST	SKRA	SKHM	SKHU	SKTD	SKSN	SKSL	SKSC	SKRT	SKRV	SKRH
Photo		NEW 				NEW 						
Features		Middle travel		—	—	Low–profile	Mid-mount	Half-mount	Low–profile	—	4–direction switch+push switch	
Water-proof		—	○	—	○	●	—	—	—	—	—	—
Dust-proof		○	○	—	○	●	○	○	○	—	—	—
Operating direction	Toppush	●	●	●	●	—	—	—	—	—	●	●
	Sidepush	—	—	—	—	●	●	●	●	●	—	—
Dimensions (mm)	W	8.5	□ 6.2	6.2	6.2	2.9	6.2	4.5	3.5	4.5	6.45	7.35
	D	8.5		6.5	6.3	3.9	2.55	2.6	3.55		6.4	7.5
	H	3.95	3.4	3.1	2.5	1.55	3.5	2.2	1.25	3.3	4	5
Operation force coverage	~1N										※	
	1N~2N											
	2N~3N											
	3N~4N											
	4N~5N											
Travel (mm)		0.9	※	0.25		0.15	0.2	0.15	0.2		※	
Ground terminal		—	—	●	●	●	●	●	●	●	—	—
Operating temperature range		-30℃ to +85℃					-40℃ to +90℃		-30℃ to +85℃		-20℃ to +70℃	-40℃ to +85℃
Automotive use		●	○	—	○	—	—	—	—	—	—	—
Life Cycle		★2	★3	★3	★3	★2	★2	★2	★2	★2	★2	★2
Rating (max.) (Resistive load)		50mA 16V DC	50mA 12V DC									
Rating (min.) (Resistive load)		10μA 1V DC										
Electrical performance	Insulation resistance	100MΩ min. 100V DC for 1min.										
	Voltage proof	250V AC for 1min.							100V AC for 1min.	250V AC for 1min.	100V AC for 1min.	
Durability	Vibration	10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2hours respectively										
	Lifetime	Shall be in accordance with individual specifications.										
Environmental performance	Cold	-30±2℃ for 96h					-40℃ for 96h		-30±2℃ for 96h			-40±2℃ for 96h
	Dry heat	80±2℃ for 96h					90℃ for 96h		80±2℃ for 96h			90±2℃ for 96h
	Damp heat	60±2℃, 90 to 95%RH for 96h										
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W : Width. The most outer dimension excluding terminal portion.
D : Depth. The most outer dimension excluding terminal portion.
H : Height. The minimum dimension if there are variances.

● TACT Switch™ Soldering Conditions 288
● TACT Switch™ Cautions 289

Notes

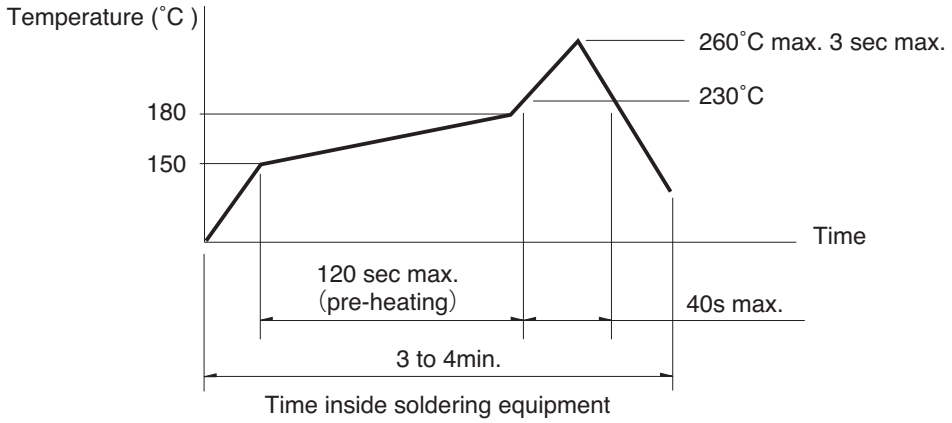
1. The automotive operating temperature range to be individually discussed upon request.
2. ● indicates applicability to all products in the series, while ○ indicates applicability to some products in the series.
3. ※ See the relevant pages for respective product descriptions

TACT Switch™ Soldering Conditions

Condition for Reflow

Available for Surface Mount Type.

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at solder joints (copper foil surface).
   A heat resistive tape should be used to fix thermocouple.
3. Temperature profile



Time inside soldering equipment

Notes

1. The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others. The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip

Available for Snap-in Type and Radial Type

Items	Condition
Flux built-up	Mounting surface should not be exposed to fluk
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100℃ max.
Preheating time	60s max.
Soldering temperature	260℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH、SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to fluk
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110℃ max.
Preheating time	60s max.
Soldering temperature	260℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKQJ、SKQK、SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to fluk
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100℃ max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

Manual Soldering (Except SKRT Series)

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKHH、SKHW、SKRG、SKPD Series

Items	Condition
Soldering temperature	360℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKQJ、SKQK、SKEG Series

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

Notes

1. Consult with us for availability of TACT Switch™ washing.
2. Prevent flux penetration from the top side of the TACT Switch™.
3. Switch terminals and a PC board should not be coated with flux prior to soldering.
4. The second soldering should be done after the switch is stable with normal temperature.
5. Use the flux with a specific gravity of min 0.81.
   (EC-19S-8 by TAMURA Corporation, or equivalents.)